



US00D953300S

(12) **United States Design Patent** (10) **Patent No.:** **US D953,300 S**
Li (45) **Date of Patent:** **** May 31, 2022**

(54) **EARPHONES**

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(51) **LOC (13) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/223**

(58) **Field of Classification Search**
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128/866; 381/380, 381; 455/90.3, 575.1,
455/569.1
CPC H04R 1/10; H04R 25/00; H04R 25/02;
H04R 1/1016; H04R 1/1066; H04R
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H04R 1/1091
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for earphones, as shown and described.

DESCRIPTION

FIG. 1 is a top, front, left side perspective view of earphones, showing my design.

FIG. 2 is a front elevation view thereof.

FIG. 3 is a rear elevation view thereof.

FIG. 4 is a left side elevation view thereof.

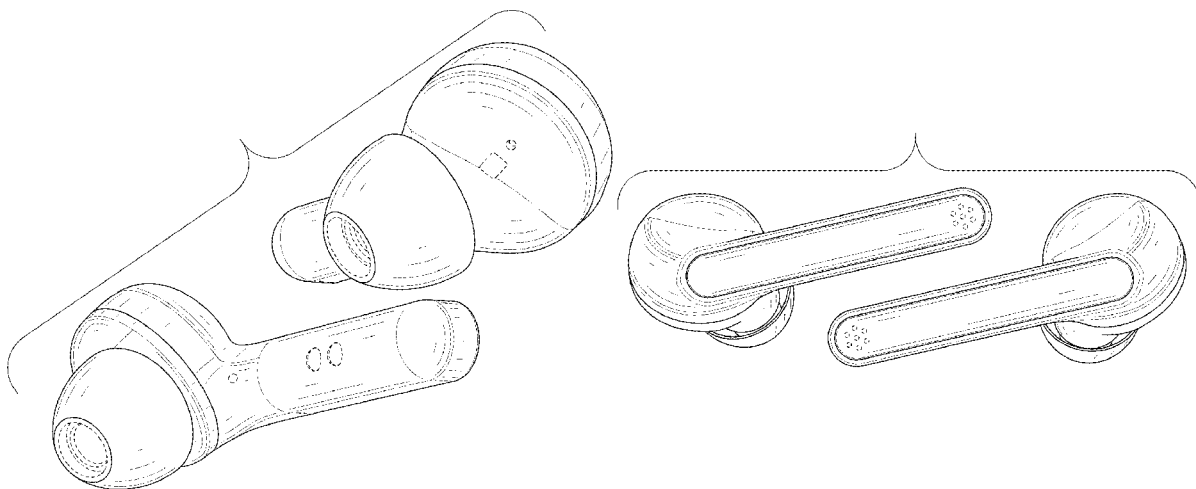
FIG. 5 is a right side elevation view thereof.

FIG. 6 is a top plan view thereof; and,

FIG. 7 is a bottom plan view thereof.

The broken line depict portions of the earphones that form no part of the claimed design.

1 Claim, 7 Drawing Sheets



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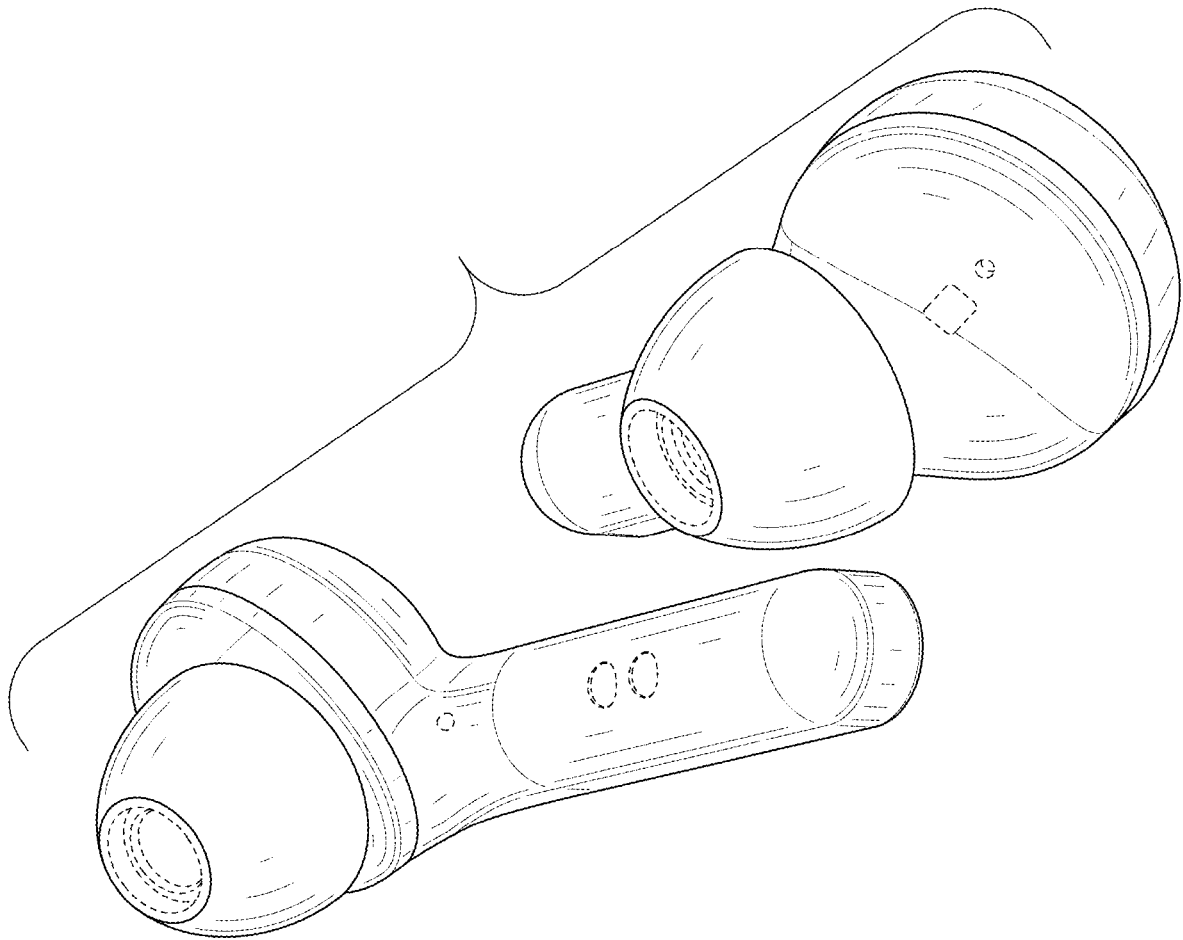


FIG. 1

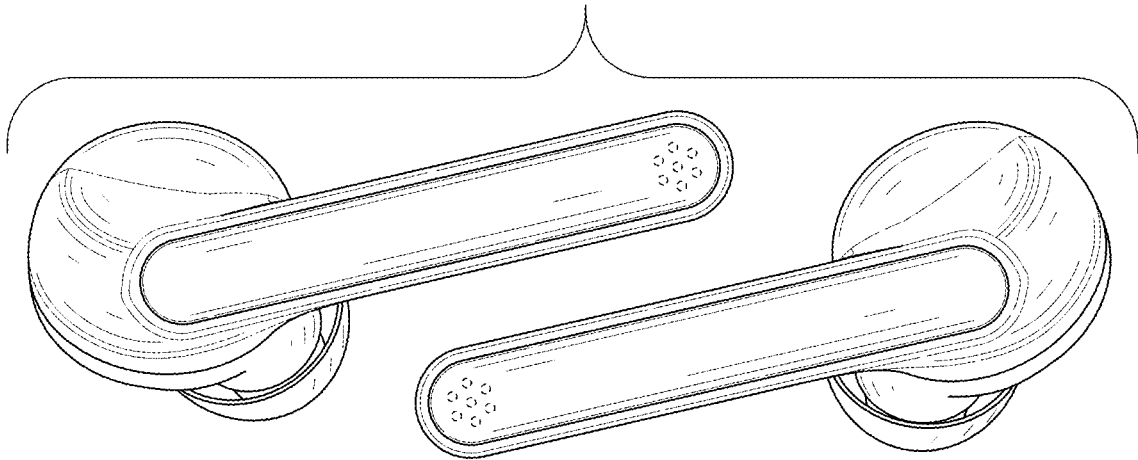


FIG. 2

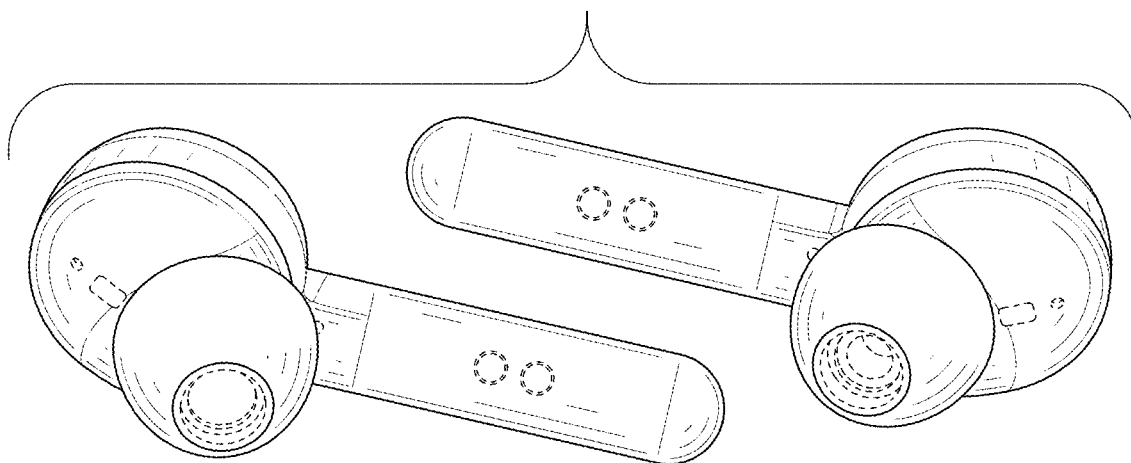


FIG. 3

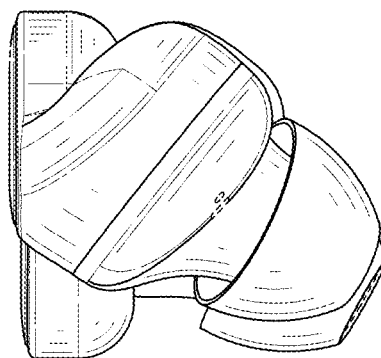


FIG. 4

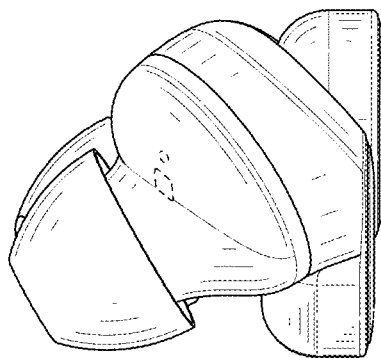


FIG. 5

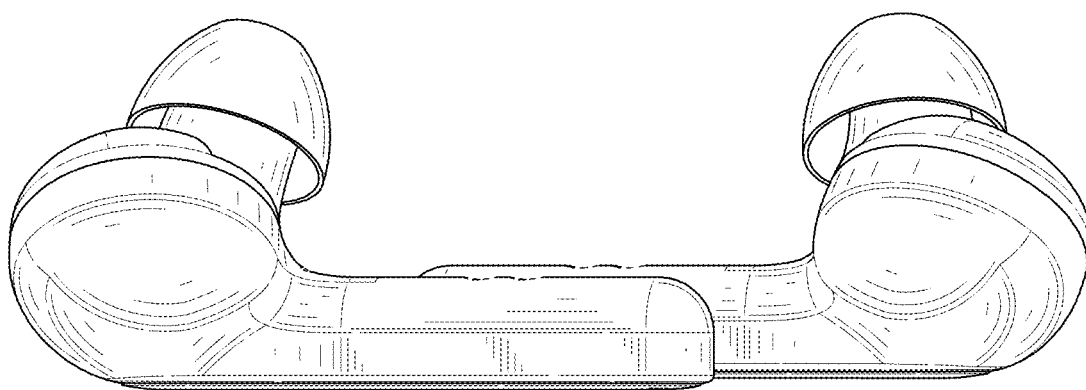


FIG. 6

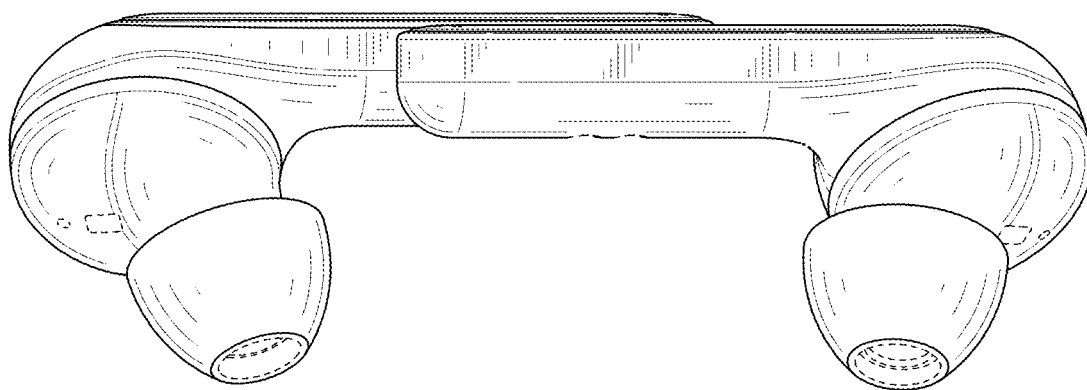


FIG. 7